

# TO-252

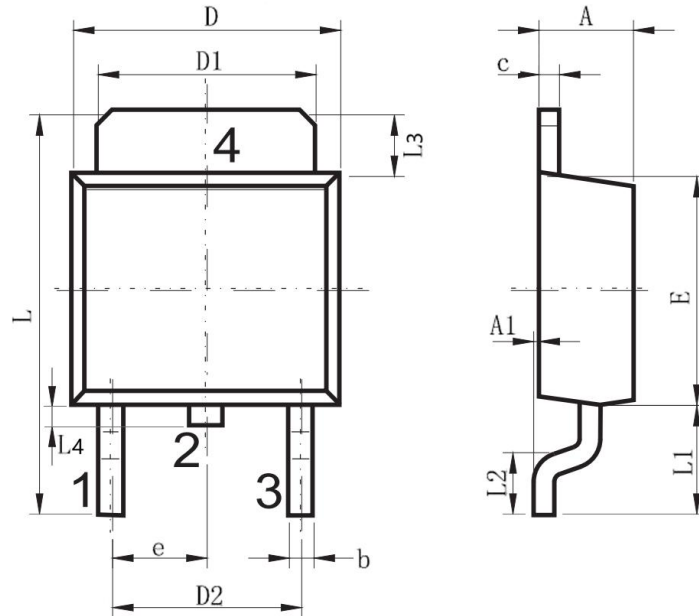
**Plastic, surface-mounted package; 3 terminals;  
2.286 mm pitch; 6.1 mm x 6.6 mm x 2.3 mm body**  
塑料表面贴装封装；3 引脚；间距 2.286 mm；  
封装本体尺寸 6.1 mm x 6.6 mm x 2.3 mm

## 1. Mechanical Data 封装数据

Feature 特性	Description 描述
Package 封装	TO-252
Moisture Sensitivity Level 湿敏感度等级	J-STD-020 MSL1
Mounting Method Type 安装方式类型	Surface Mount Package 表面贴装封装
Material 材料	Molded Plastic, “Green” Molding Compound; UL Flammability Classification Rating 94V-0. 模塑塑料封装，“绿色”成型复合材料；UL 可燃性等级 94V-0。
Dimensions 尺寸	2.286mm pitch; 6.1mm × 6.6mm × 2.3mm body 相邻引脚中心距为 2.286mm，封装本体(不含引脚)尺寸为 6.1mm × 6.6mm × 2.3mm
Terminals Compliance 引脚合规	3 terminals, Tin Plated Leads; exposed die pad for good heat transfer; Solderable per MILSTD-202, Method 208 <sup>e3</sup> 3 个镀锡引脚，外露散热焊盘以增强热传导；可焊性符合 MIL-STD-202 标准中 208 方法 e3 条款的要求
Weight 重量	2.24 grams (Approximate) 约 2.24 克

## 2. Package Outline Dimensions 封装外形尺寸

TO-252



Symbol 符号	Millimeters 毫米	
	Min.最小值	Max.最大值
A	2.10	2.50
A1	-	0.127
b	0.50	0.90
c	0.30	0.70
D	6.30	6.70
D1	5.10	5.50
D2	4.4	4.8
E	5.50	6.30
e	2.10	2.50
L	9.70	10.10
L1	2.70	3.10
L2	1.40	1.78
L3	1.20	1.60
L4	-	1.01

### 3. Suggested Pad Layout 推荐焊盘布局

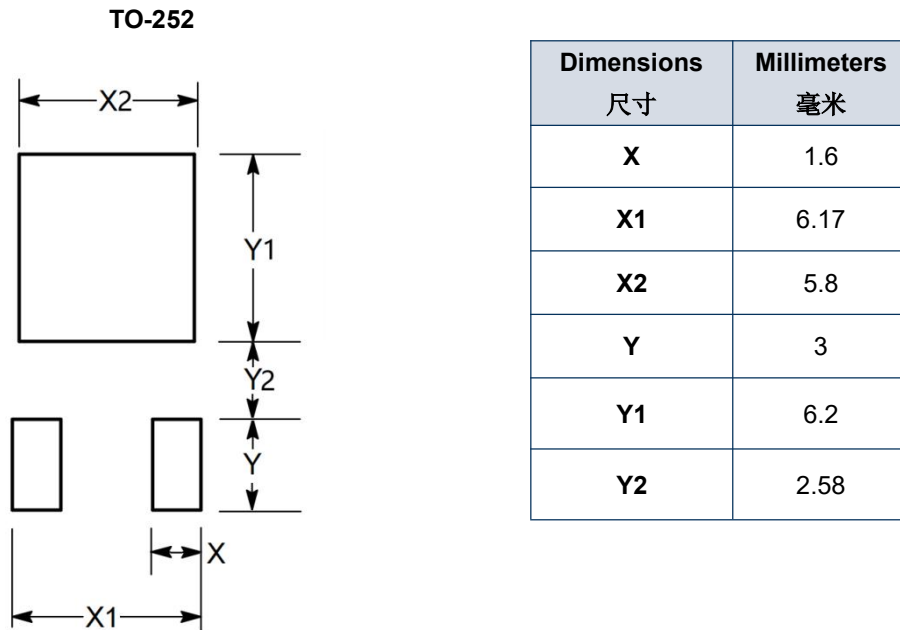


Fig. Soldering footprint for TO-252

图 TO-252 的引脚焊接

### 4. Minimum Packing Quantity 最小包装数量

Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
13	16	2500

**Note:**

Package quantities given are for minimum packaging quantity only, not minimum order quantity. For minimum order quantity, please contact Sales Department.

**说明:** 上表所列包装数量仅为最低包装数量，并非最低订购数量。如需最低订购数量，请联系销售部门。



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